

Supporting Information

Title Metal-Agglomeration-Suppressed Growth of MoS₂ and MoSe₂ Films with Small Sulfur and Selenium Molecules for High Mobility Field Effect Transistor Applications

Kwang Hoon Jung, Sun Jin Yun, Yongsuk Choi, Jeong Ho Cho, Jung Wook Lim, Hyun-Jun Chai, Dae-Hyung Cho, Yong-Duck Chung, and Gayoung Kim*

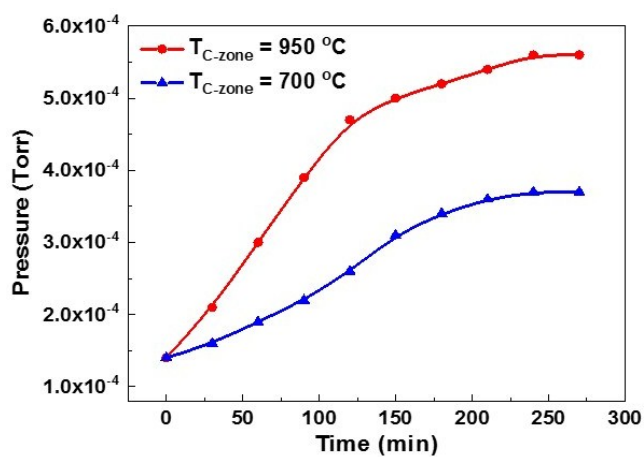


Figure S1. Change in chamber pressure with respect to time at T_{C-zone} = 700 and 950 °C.

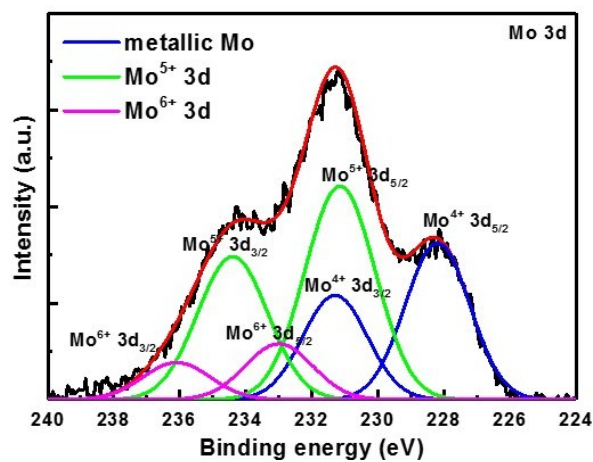


Figure S2. Mo 3d XPS spectrum of Mo film that was deposited to be 2 nm-thick using e-beam evaporation and exposed to air. The component peaks indicate that elemental Mo, oxidized Mo (Mo⁵⁺ and Mo⁶⁺) bonding states coexist in the film. The ratio of different oxidation states of Mo was metallic Mo : Mo⁵⁺ : Mo⁶⁺ = 35 : 52 : 13, and the partially oxidized Mo-precursor film was approximately 2.5 nm-thick.

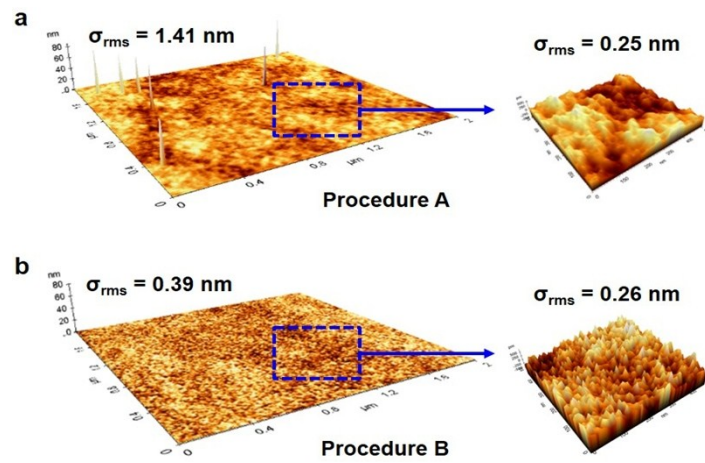


Figure S3. AFM images ($2 \mu\text{m} \times 2 \mu\text{m}$) and rms roughness (σ_{rms}) values of MoS_2 films ($T_G=500 \text{ }^\circ\text{C}$) of (a) procedure A and (b) procedure B. The σ_{rms} value of a region with no protrusions (procedure A) was also compared with that of procedure B in a selected small area ($500 \text{ nm} \times 500 \text{ nm}$).

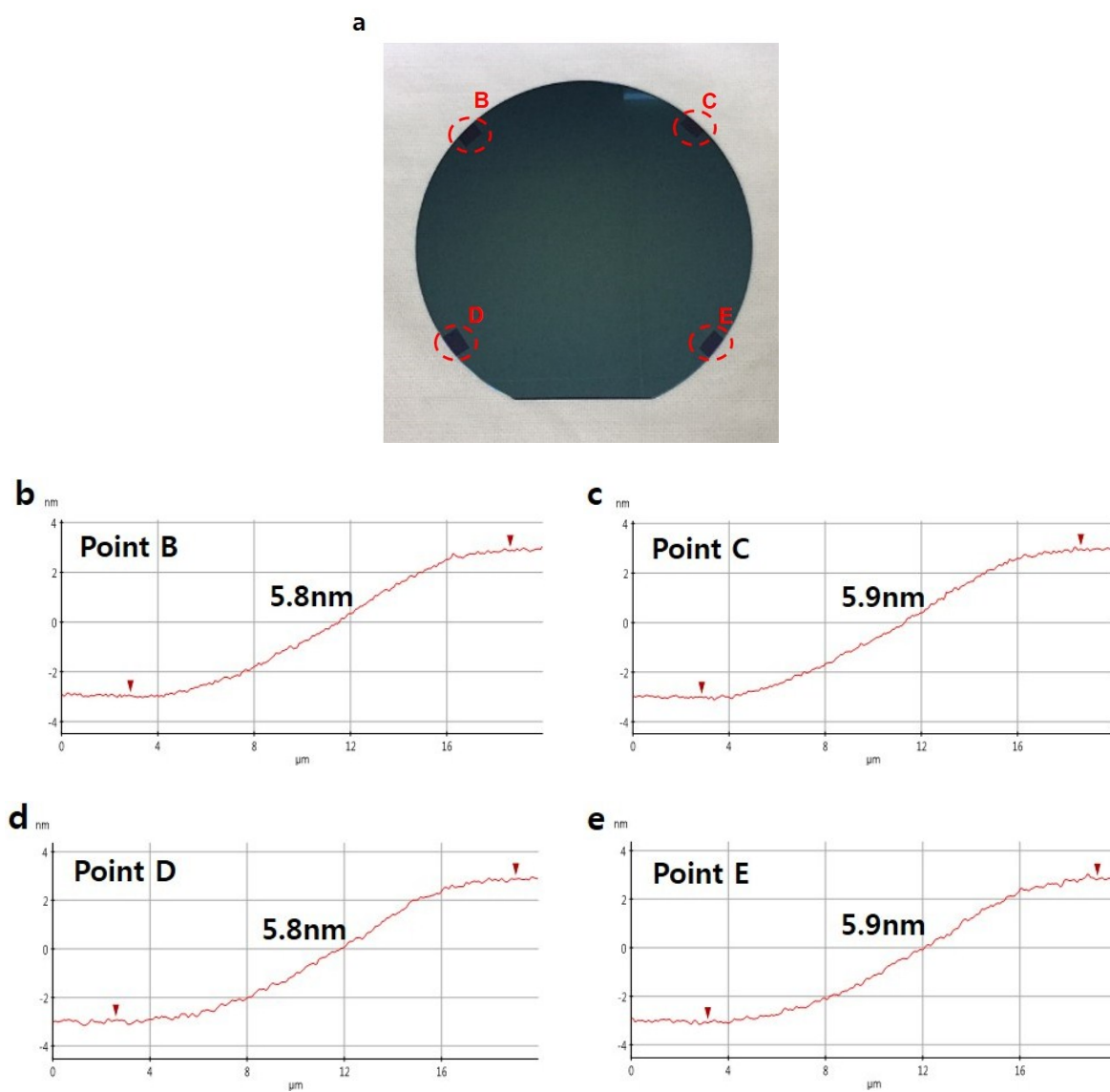


Figure S4. (a) Photograph of a high quality MoS₂ film on a 6 inch SiO₂/Si wafer. Height profiles of the MoS₂ film at points (b) B, (c) C, (d) D, and (e) E.

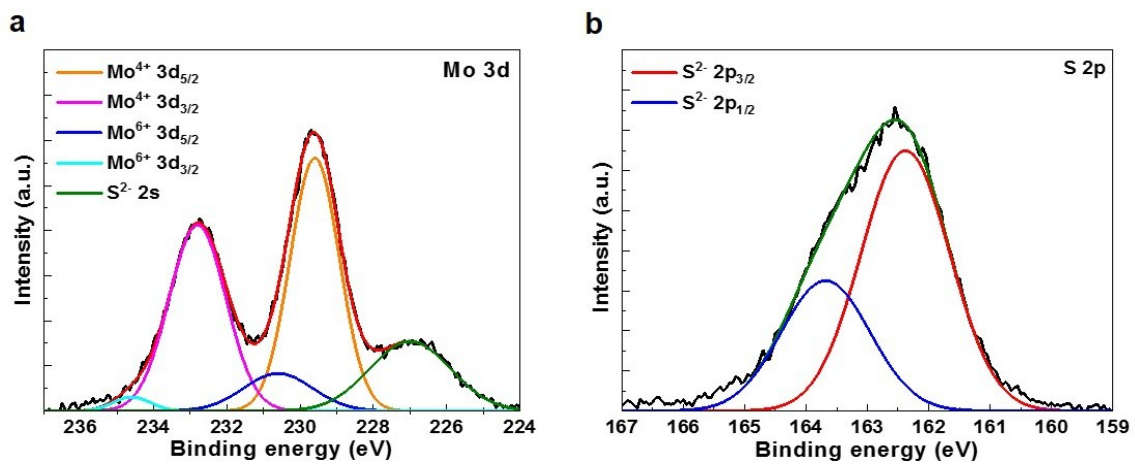


Figure S5. XPS peaks of (a) Mo and (b) S in a 6 nm-thick MoS₂ film fabricated at $T_{R\text{-zone}} = 120\text{ }^{\circ}\text{C}$.

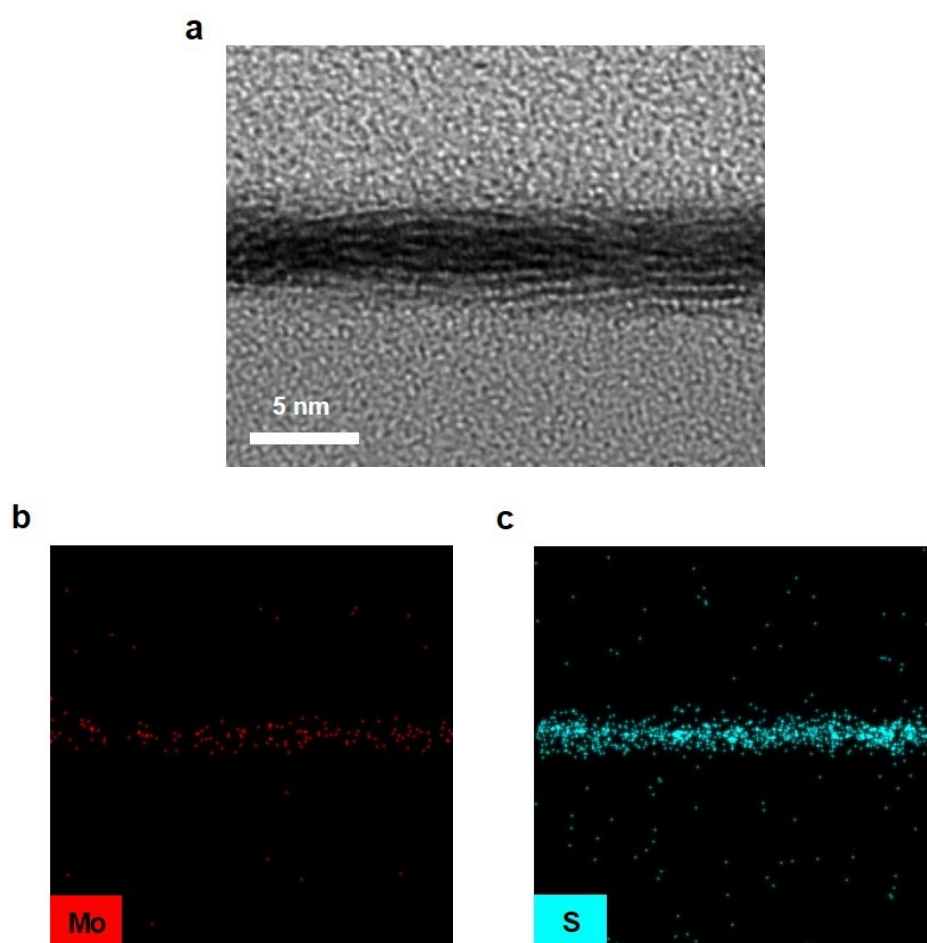


Figure S6. (a) A cross-sectional TEM image of a 3.1 nm-thick MoS₂ film. EDS maps of (b) Mo and (c) S in a 3.1 nm-thick MoS₂ film.

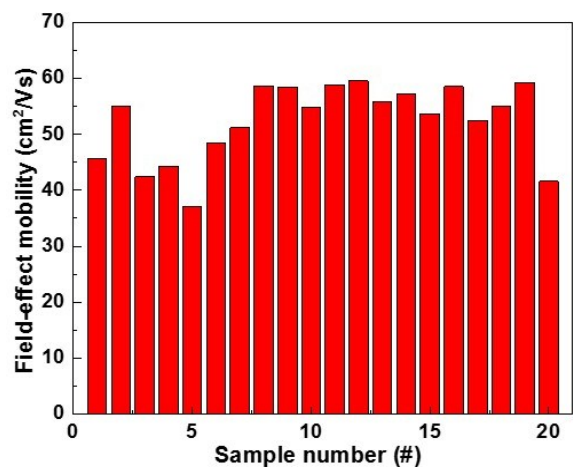


Figure S7. Histogram of field-effect mobility of MoS₂-FETs for 20 devices fabricated on a substrate.